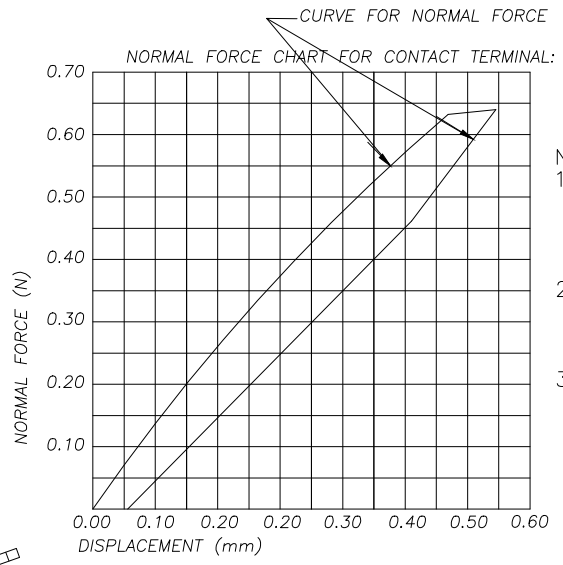
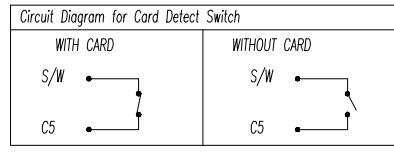
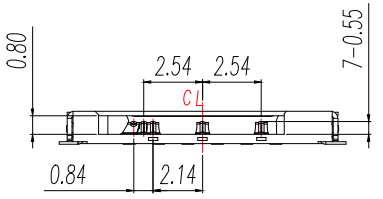
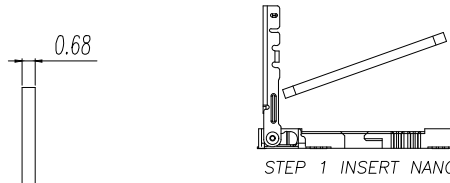
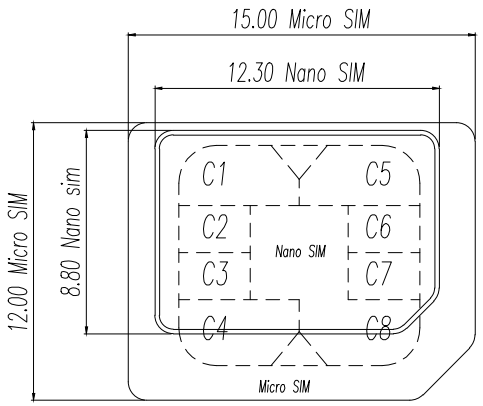


NANO SIM CARD	
Pin No.	NAME
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	I/O OF SIM
C4/C8	N/A
S/W	Switch Pin



- NOTES:
- MATERIAL:
    - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
    - Terminal: Copper Alloy, T=0.12mm.
    - Shell: Stainless Steel, T=0.20mm.
  - FINISH:
    - Terminal: Plated Gold on The Contact Area and Solder Tails
    - Peg: Plated Gold on the Solder Tails.
  - SPECIALITY:
    - Rated current: 0.5A
    - Rated voltage: 50V
    - Contact Resistance: 80mΩMAX
    - Insulation Resistance: 100MΩMIN 100V DC
    - Dielectric withstanding voltage: 100V AC.
    - Solder ability: 245±5°C, 5±0.5s.
    - Operating condition: Temperature: -40°C~+85°C Humidity: 80% R.H MAX

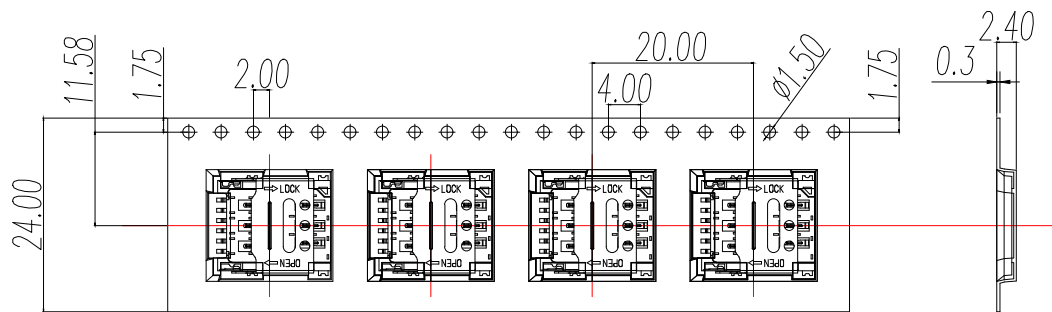


制图	变更内容	日期	GENERAL TOLERANCE		制图	EMMA		料号	BX-SMN-1.4HJ-F		版本	A
DRAWN	DESCRIPTION	DATE	X±0.50	X'±2"	DRAWING	EVA		PART NO.	7pin 1.4h higne nano sim card conn.		页次	1/1
			.X±0.20	.X'±1"	审核	JADE		客户料号			图例	
			.XX±0.10		批准			CUTM.NO.				
					单位	MM	比例	SCALE		1:1		

NO.	PART NAME	Q'TY	DESCRIPTION	NOTE
③	TERMINAL	6	C5210-EH, T=0.12	Au 3u" PLATING
②	BASE INSULATOR	1	LCP+GF30%	BLACK
①	SHELL	1	SUS304-H, T=0.15	AU/Ni PLATING



图示(一) 载带



NOTES:

1, 每盘包装 1500PCS 产品.

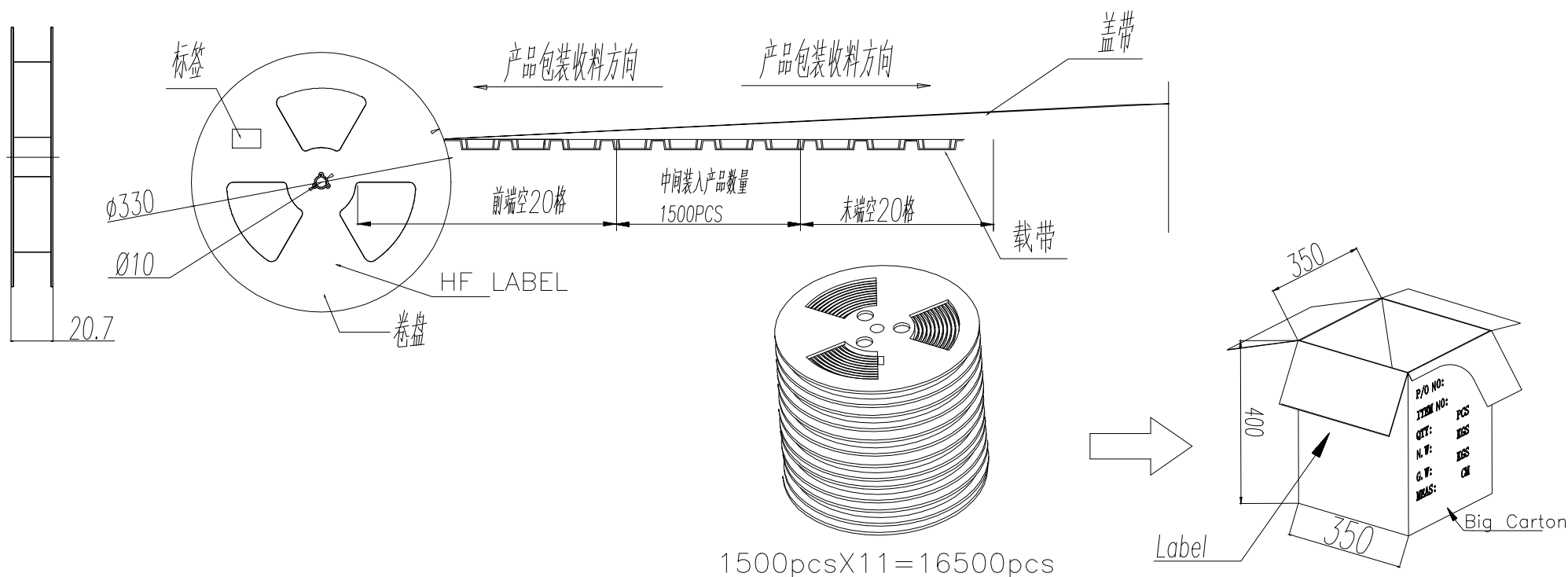
包装要求如图示(二)

2, 每箱包装数量 16500PCS. 纸箱外则以胶带封口成 (工) 字型.

3, 上载带剥离不速度: 300mm/minutes.

4, 卷带封合力小于 100G.

图示(二) 圆盘包装



制图 DRAWN	变更内容 DESCRIPTION	日期 DATE	GENERAL TOLERANCE		制图 DRAWING	EMMA	料号 PART NO.	BX-SMN-1.4HJ-F	版本 REV.	A
			X.±0.50	X.±2°						
			.X±0.20	.X±1°	审核 CHECK	EVA	品名 TITLE	7pin 1.4h higne namo sim card conn.材料	页次 SHEET	1/1
			.XX±0.10		批准 APPROVAL	JADE	客户料号 CUTM.NO.			
					单位 UNITS	MM	比例 SCALE	1:1		

**JB Bossie (博锡)**